

Amendments to the Specification:

Please add the following new paragraph immediately following the title on page 1:

--CROSS REFERENCE TO RELATED APPLICATION(S)

The present application is a continuation of U.S. serial no. 10/172,415 filed on June 14, 2002.--

Please delete the original abstract at page 27 and add the following new abstract:

--A method for fabricating a circuit device includes preparing a laminating sheet comprising a conductive film, insulation resin formed on the surface of the conductive film, and a first conductive path layer formed on the surface of the insulation resin. Semiconductor elements are adhered and fixed on the first conductive path layer. A sealing resin is provided as an overcoat to the first conductive path layer and the semiconductor elements. The method includes forming a second conductive path layer by etching the conductive film into a predetermined pattern and forming an external electrode at predetermined points of the second conductive path layer.--